



PNE20040CPE

200 V, 2 x 2 A dual common cathode hyperfast recovery rectifier

29 October 2021

Product data sheet

1. General description

High power density, hyperfast switching time dual recovery rectifier in common cathode configuration with high-efficiency planar technology, encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Reverse voltage: $V_R \leq 200$ V
- Forward current: $I_F \leq 2$ A (per diode)
- Switching time: $t_{tr} \leq 25$ ns
- Pt doped life time control
- Low inductance
- Power and flat lead SMD plastic package
- Package height typical 0.95 mm
- High power capability due to clip-bond technology
- Planar die design

3. Applications

- General-purpose rectification
- Hyperfast switching
- Solenoid control
- Piezo injection
- Freewheeling applications

4. Quick reference data

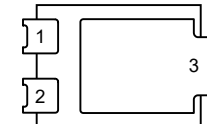
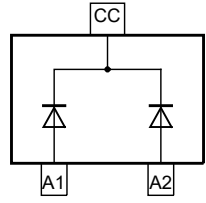
Table 1. Quick reference data

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|---|---------------------------------|--|-----|-----|-----|-----|------|
| Per diode (unless otherwise specified) | | | | | | | |
| $I_{F(AV)}$ | average forward current | $\delta = 0.5$; $f = 20$ kHz; square wave; $T_{sp} \leq 167$ °C | | - | - | 2 | A |
| V_{RRM} | repetitive peak reverse voltage | $T_j = 25$ °C | | - | - | 200 | V |
| V_R | reverse voltage | | | - | - | 200 | V |
| V_F | forward voltage | $I_F = 2$ A; $T_j = 25$ °C | [1] | - | 890 | 980 | mV |
| | | $I_F = 2$ A; $T_j = 125$ °C | [1] | - | 735 | 870 | mV |
| I_R | reverse current | $V_R = 200$ V; $T_j = 25$ °C | [1] | - | - | 1 | µA |
| | | $V_R = 200$ V; $T_j = 125$ °C | [1] | - | 1 | 20 | µA |

[1] Very short pulse, in order to maintain a stable junction temperature.

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-----------------|--|---|
| 1 | A1 | anode (diode 1) |  <p>CFP15B (SOT1289B)</p> |  <p>aaa-030081</p> |
| 2 | A2 | anode (diode 2) | | |
| 3 | CC | common cathode | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-------------|---------|--|----------|
| | Name | Description | Version |
| PNE20040CPE | CFP15B | plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body | SOT1289B |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PNE20040CPE | 200E 004C |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC60134)

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|---|-------------------------------------|--|-----|-----|------|------|
| Per diode (unless otherwise specified) | | | | | | |
| V_R | reverse voltage | $T_j = 25\text{ °C}$ | | - | 200 | V |
| V_{RRM} | repetitive peak reverse voltage | | | - | 200 | V |
| $V_{R(RMS)lim}$ | limiting RMS reverse voltage | | | - | 140 | V |
| I_F | forward current | $\delta = 1; T_{sp} \leq 164\text{ °C}$ | | - | 2.8 | A |
| $I_{F(AV)}$ | average forward current | $\delta = 0.5; f = 20\text{ kHz};$ square wave; $T_{sp} \leq 167\text{ °C}$ | | - | 2 | A |
| I_{FSM} | non-repetitive peak forward current | $t_p = 8.3\text{ ms};$ single half sine wave (applied at rated load condition); $T_{j(init)} = 25\text{ °C}$ | | - | 55 | A |
| | | $t_p = 8.3\text{ ms};$ single half sine wave (applied at rated load condition); per device; $T_{j(init)} = 25\text{ °C}$ | | - | 100 | A |
| Per device, one diode loaded | | | | | | |
| P_{tot} | total power dissipation | $T_{amb} \leq 25\text{ °C}$ | [1] | - | 1.66 | W |
| | | | [2] | - | 2.15 | W |
| T_j | junction temperature | | | - | 175 | °C |
| T_{amb} | ambient temperature | | | -55 | 175 | °C |
| T_{stg} | storage temperature | | | -65 | 175 | °C |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit | |
|-------------------------------------|--|-------------|-----|-----|-----|------|-----|
| Per device, one diode loaded | | | | | | | |
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] | - | - | 90 | K/W |
| | | | [2] | - | - | 70 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | [3] | - | - | 7 | K/W |

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [3] Soldering point of cathode tab.

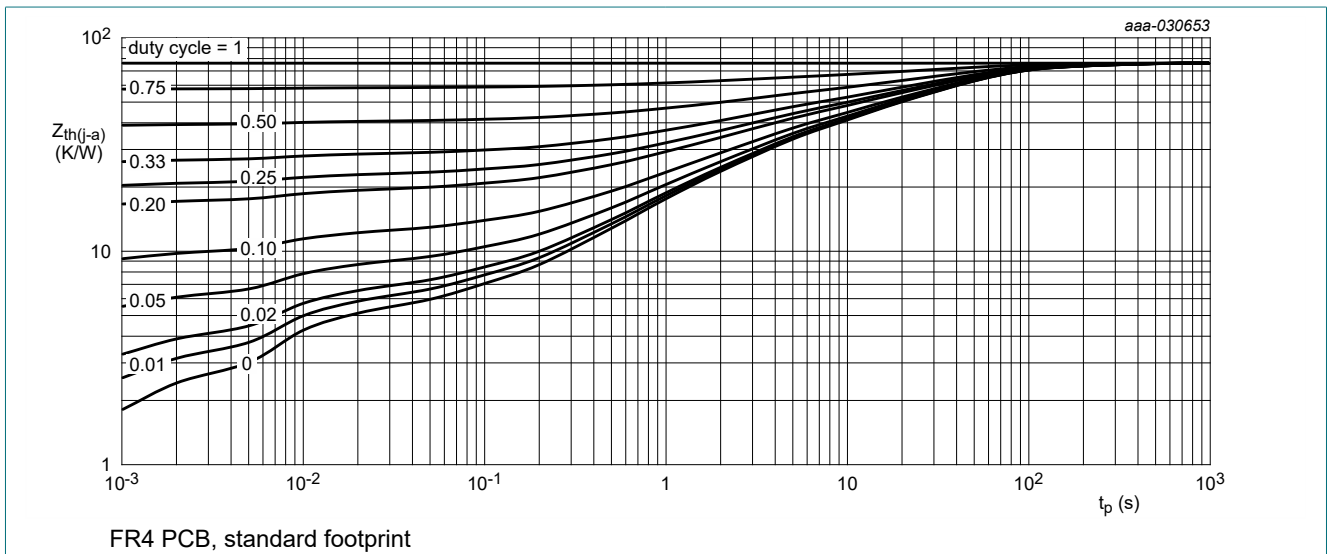


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

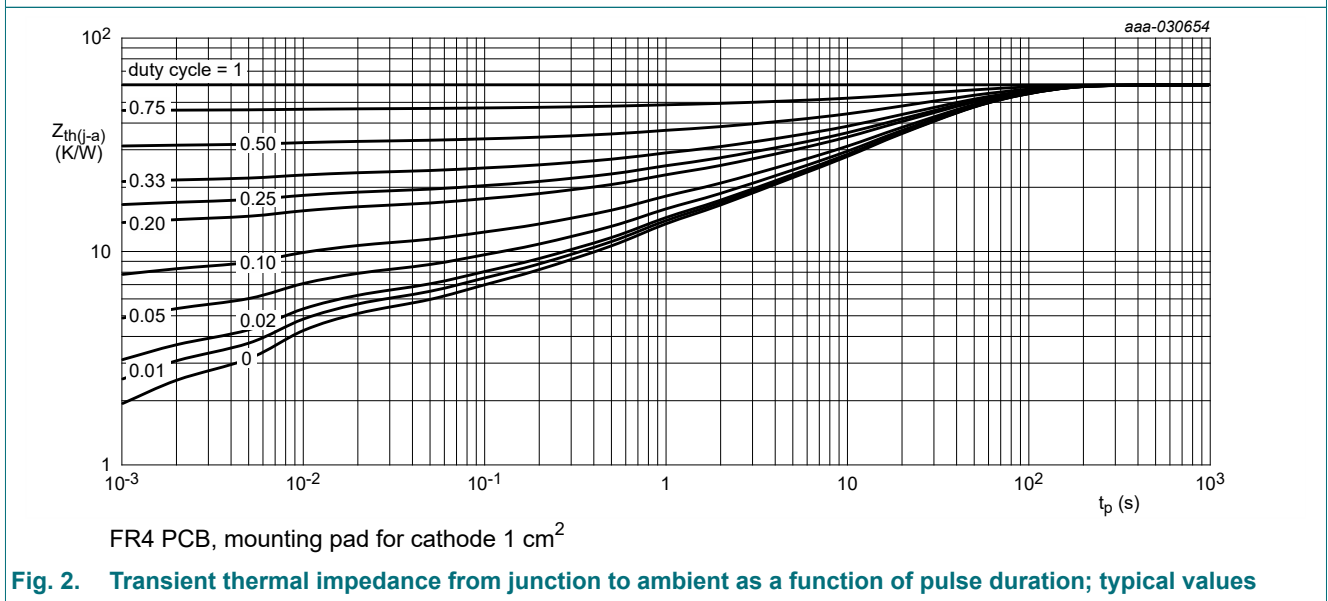


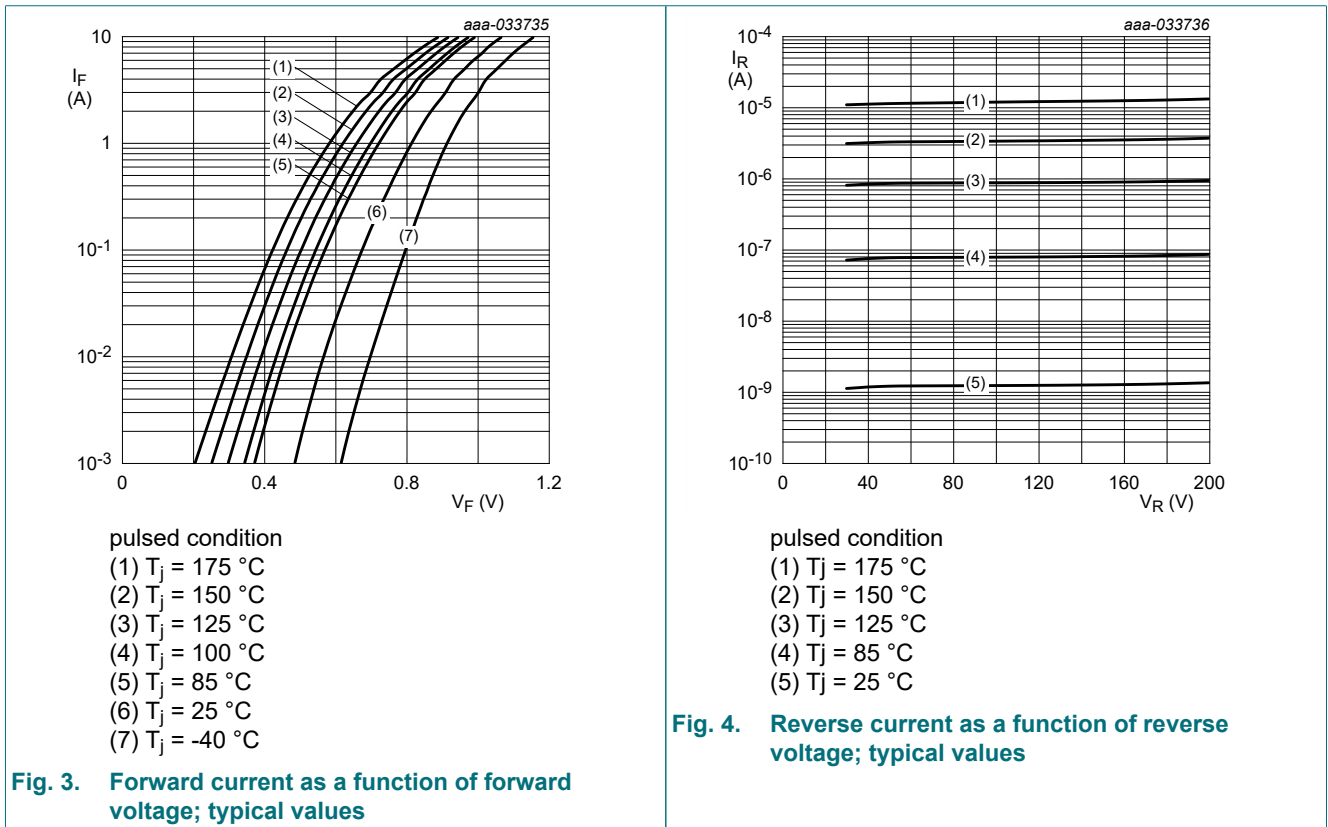
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

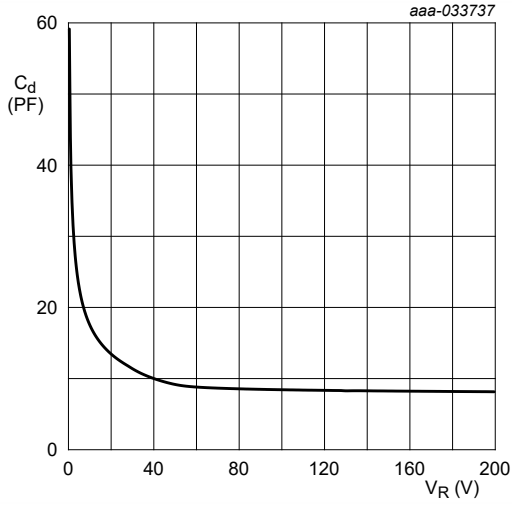
10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit | |
|---|-------------------------------------|---|-----|-----|-----|------|---------|
| Per diode (unless otherwise specified) | | | | | | | |
| $V_{(BR)R}$ | reverse breakdown voltage | $I_R = 100 \mu A; T_j = 25 \text{ }^\circ C$ | [1] | 200 | - | V | |
| V_F | forward voltage | $I_F = 2 \text{ A}; T_j = 25 \text{ }^\circ C$ | [1] | - | 890 | 980 | mV |
| | | $I_F = 2 \text{ A}; T_j = 125 \text{ }^\circ C$ | [1] | - | 735 | 870 | mV |
| I_R | reverse current | $V_R = 200 \text{ V}; T_j = 25 \text{ }^\circ C$ | [1] | - | - | 1 | μA |
| | | $V_R = 200 \text{ V}; T_j = 125 \text{ }^\circ C$ | [1] | - | 1 | 20 | μA |
| C_d | diode capacitance | $V_R = 4 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ C$ | | - | 24 | pF | |
| t_{rr} | reverse recovery time step recovery | $I_F = 0.5 \text{ A}; I_R = 1 \text{ A}; I_{R(meas)} = 0.25 \text{ A}; T_j = 25 \text{ }^\circ C$ | | - | 11 | 25 | ns |
| | reverse recovery time ramp recovery | $dI_F/dt = 50 \text{ A}/\mu s; I_F = 1 \text{ A}; V_R = 30 \text{ V}; T_j = 25 \text{ }^\circ C$ | | - | 20 | - | ns |
| | reverse recovery time | $dI_F/dt = 100 \text{ A}/\mu s; I_F = 1 \text{ A}; V_R = 30 \text{ V}; T_j = 25 \text{ }^\circ C$ | | - | 16 | - | ns |
| I_{RM} | peak reverse recovery current | $T_j = 25 \text{ }^\circ C$ | | - | 1.1 | A | |
| Q_{rr} | reverse recovery charge | | | - | 10 | nC | |
| V_{FRM} | peak forward recovery voltage | $I_F = 1 \text{ A}; dI_F/dt = 50 \text{ A}/\mu s; T_j = 25 \text{ }^\circ C$ | | - | 910 | mV | |

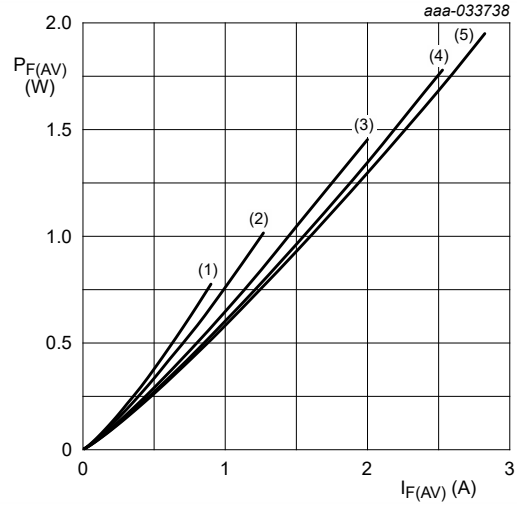
[1] Very short pulse, in order to maintain a stable junction temperature.





$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

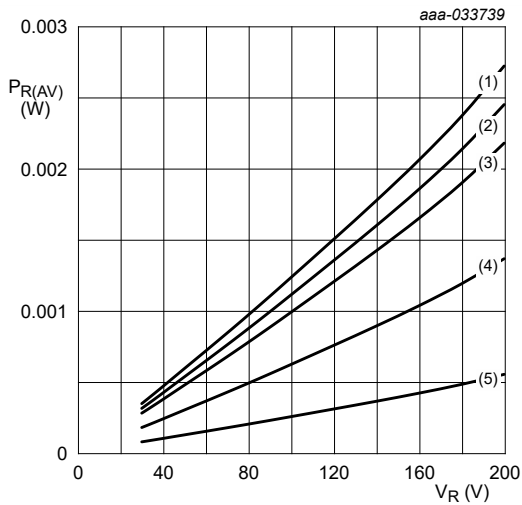
Fig. 5. Diode capacitance as a function of reverse voltage; typical values



$T_j = 175 \text{ }^\circ\text{C}$

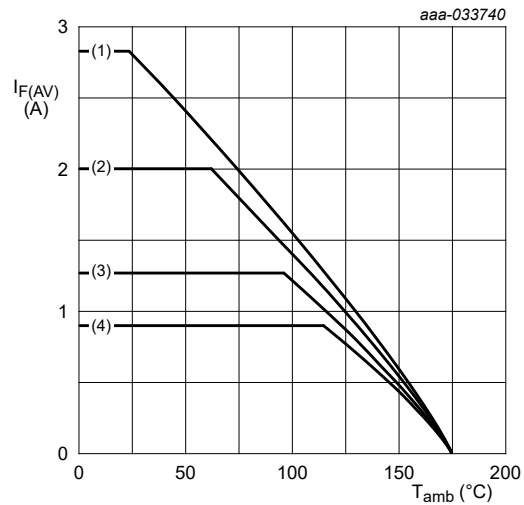
- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 0.8$
- (5) $\delta = 1; \text{DC}$

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



- $T_j = 175 \text{ }^\circ\text{C}$
- (1) $\delta = 1; \text{DC}$
 - (2) $\delta = 0.9$
 - (3) $\delta = 0.8$
 - (4) $\delta = 0.5$
 - (5) $\delta = 0.2$

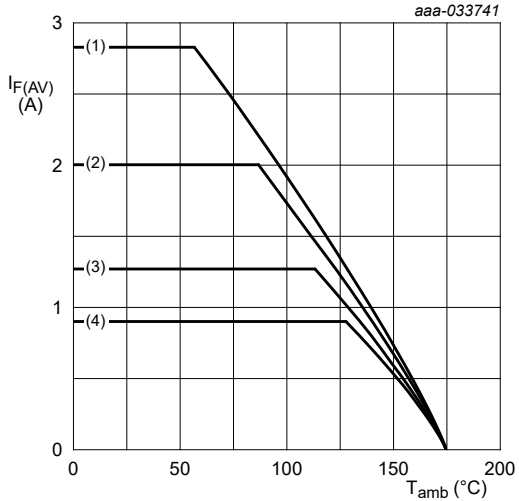
Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



- FR4 PCB, standard footprint
 $T_j = 175 \text{ }^\circ\text{C}$
- (1) $\delta = 1; \text{DC}$
 - (2) $\delta = 0.5; f = 20 \text{ kHz}$
 - (3) $\delta = 0.2; f = 20 \text{ kHz}$
 - (4) $\delta = 0.1; f = 20 \text{ kHz}$

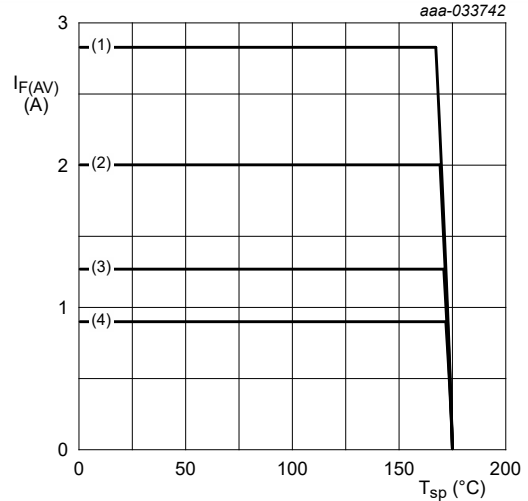
Fig. 8. Average forward current as a function of ambient temperature; typical values

200 V, 2 x 2 A dual common cathode hyperfast recovery rectifier



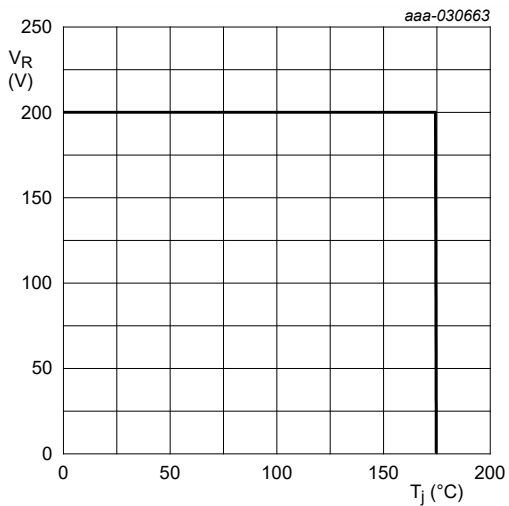
FR4 PCB, mounting pad for cathode 1 cm²
 $T_j = 175$ °C
 (1) $\delta = 1$; DC
 (2) $\delta = 0.5$; $f = 20$ kHz
 (3) $\delta = 0.2$; $f = 20$ kHz
 (4) $\delta = 0.1$; $f = 20$ kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



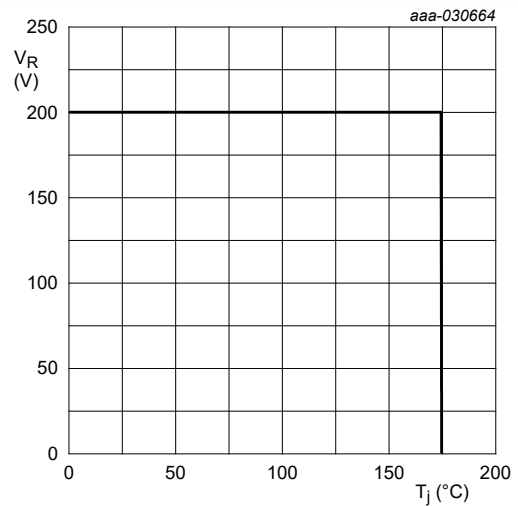
$T_j = 175$ °C
 (1) $\delta = 1$; DC
 (2) $\delta = 0.5$; $f = 20$ kHz
 (3) $\delta = 0.2$; $f = 20$ kHz
 (4) $\delta = 0.1$; $f = 20$ kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values



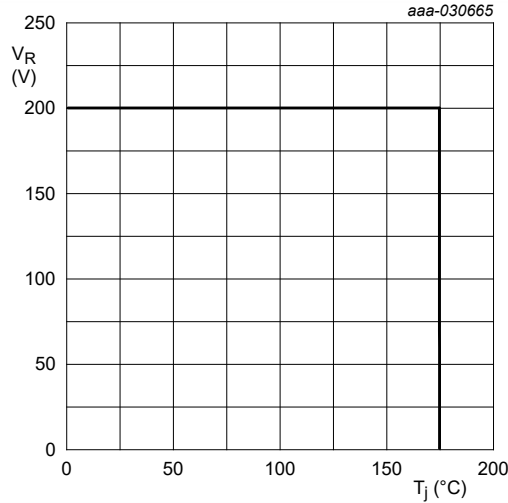
FR4 PCB, standard footprint
 $R_{th} = 90$ K/W

Fig. 11. Derated maximum reverse voltage as a function of junction temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm²
 $R_{th} = 70$ K/W

Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



Soldering point of cathode tab
 $R_{th} = 7 \text{ K/W}$

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

11. Test information

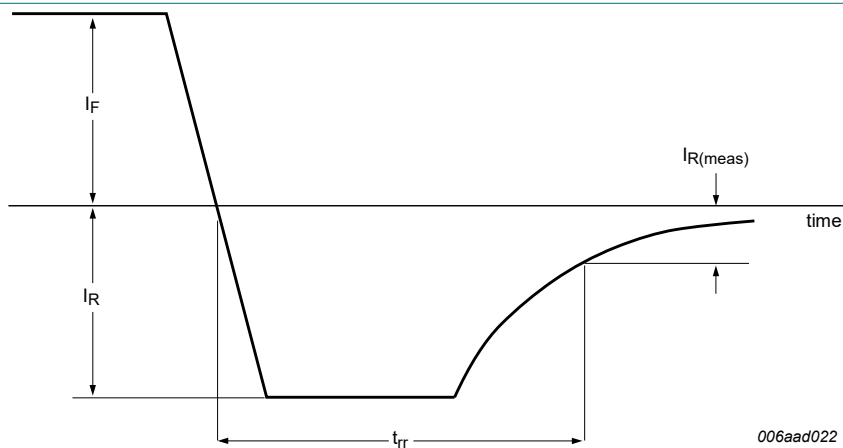


Fig. 14. Reverse recovery definition; step recovery

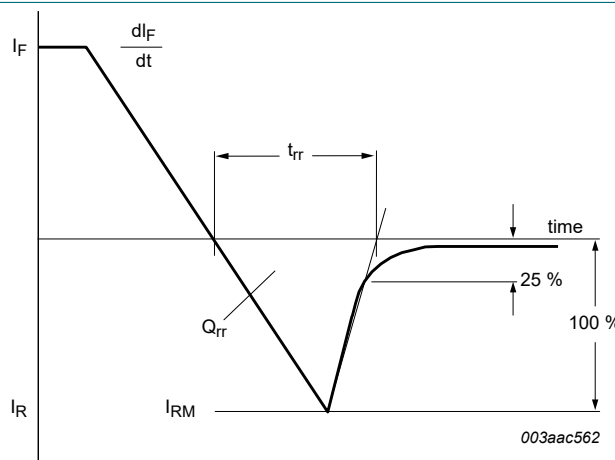


Fig. 15. Reverse recovery definition; ramp recovery

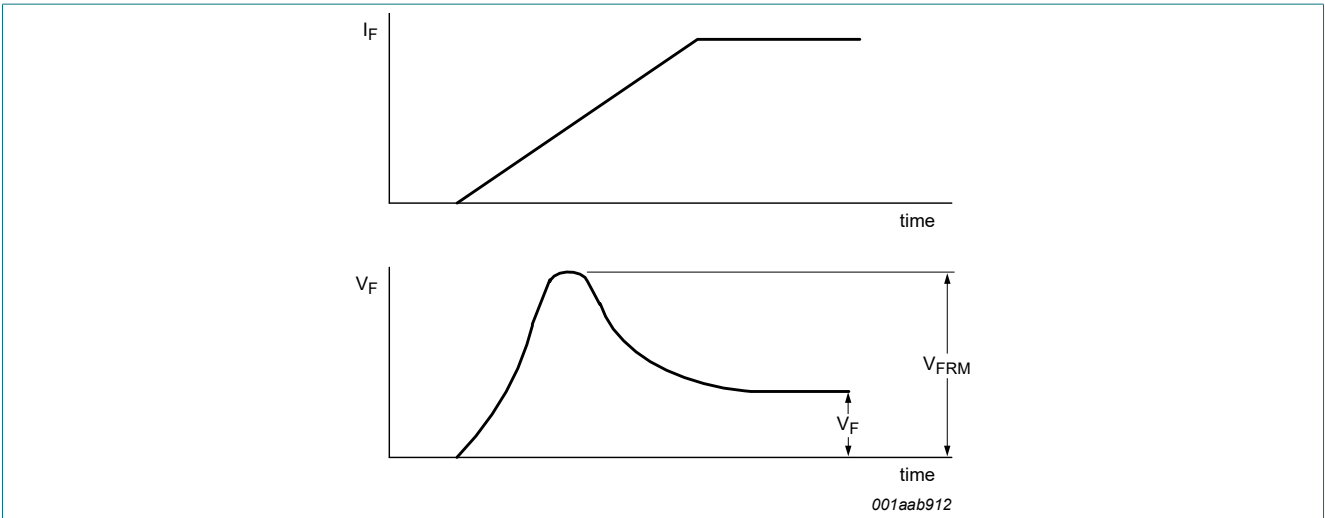


Fig. 16. Forward recovery definition

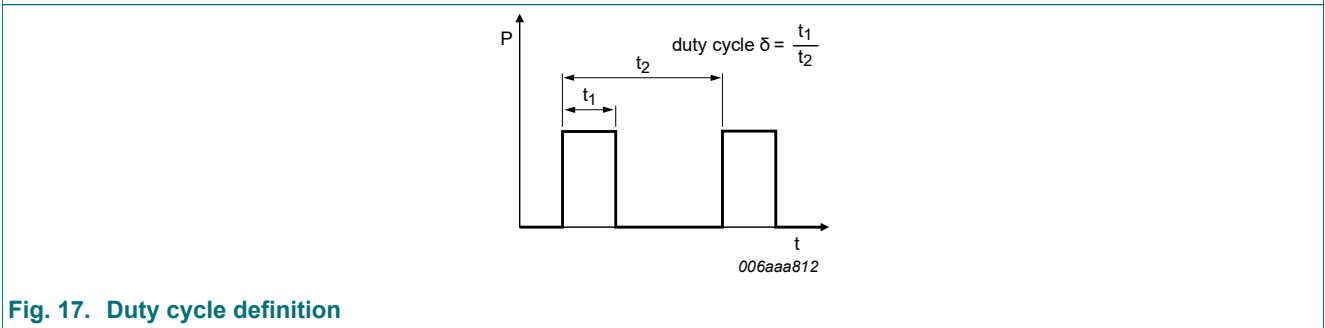


Fig. 17. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

12. Package outline

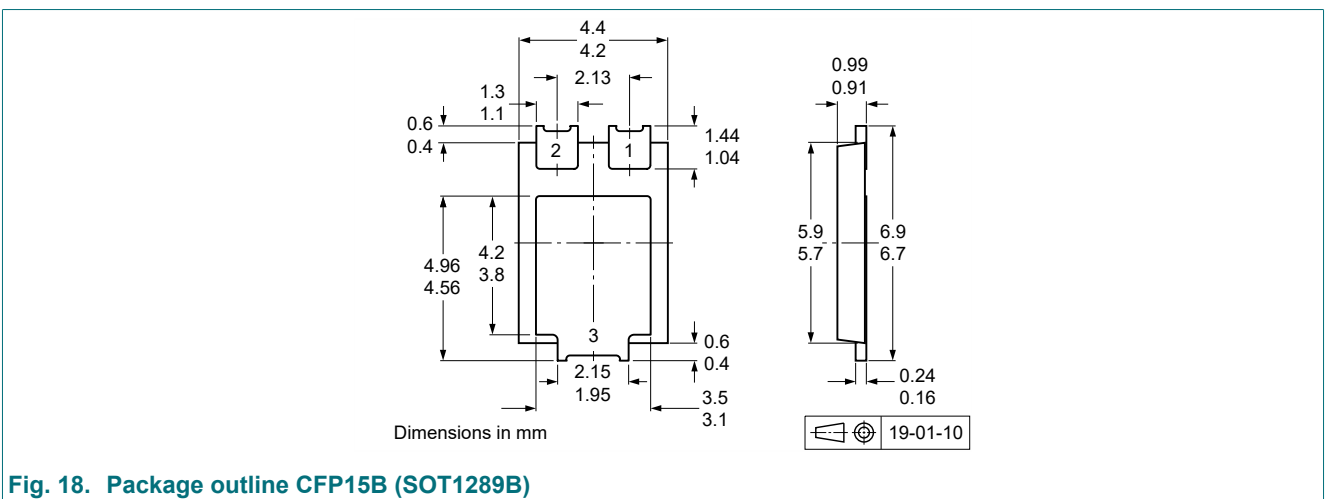


Fig. 18. Package outline CFP15B (SOT1289B)

13. Soldering

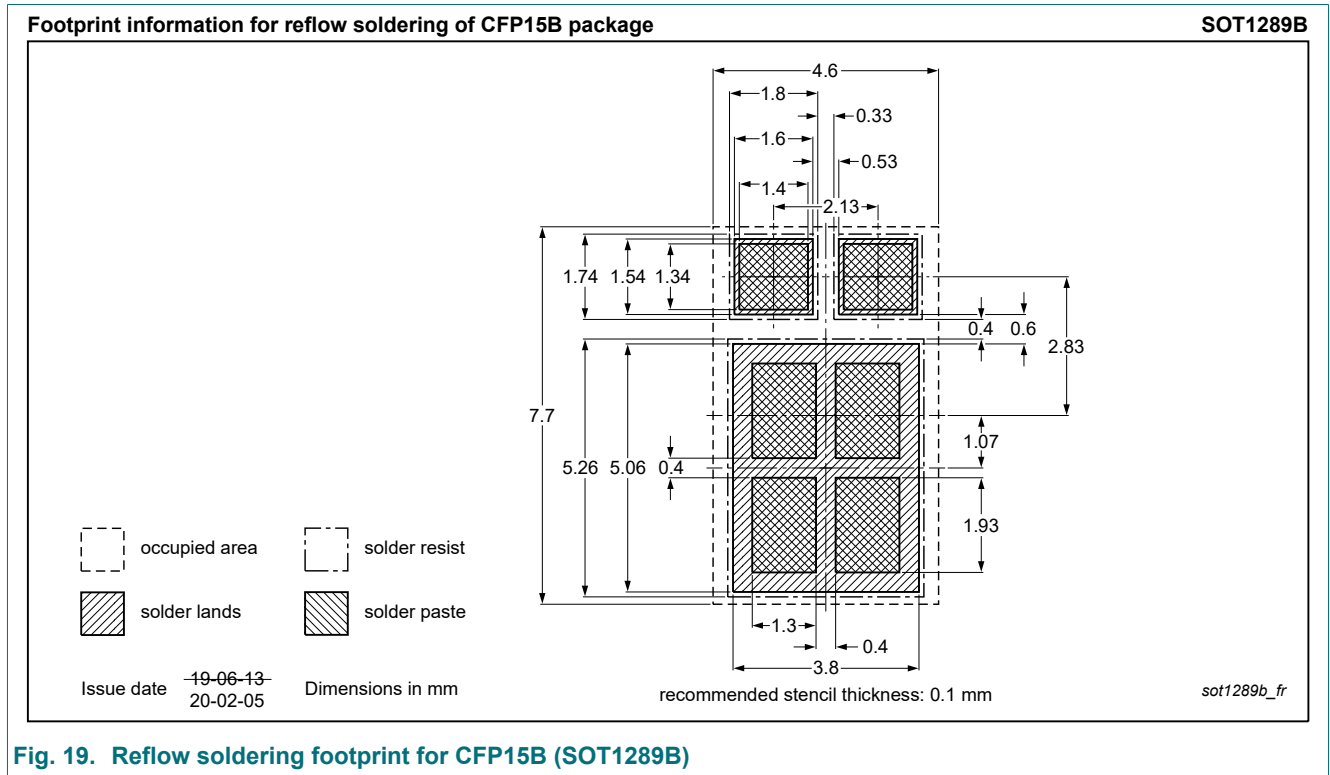


Fig. 19. Reflow soldering footprint for CFP15B (SOT1289B)

14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status | Change notice | Supersedes |
|-----------------|--------------|--------------------|---------------|------------|
| PNE20040CPE v.1 | 20211029 | Product data sheet | - | - |

15. Legal information

Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|--------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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